# Catastrophic OLED failure and pathways to address it

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## Killer shorts

OLED panels that short catastrophically:

- Decrease manufacturing yield
- Increase warranty expenses
- Decrease customer satisfaction

Highly localized current flow  $\rightarrow$  heating & irreversible damage

Origin of shorts presently unknown

To solve this problem:

- Identify incipient shorts early & determine physical origin
- Model their evolution/growth toward catastrophe
- Predict failure & develop mitigation strategies



Residue of a short



### **Hot Spots & Bright Spots**



## Bright spot microscopy

- Bright spots associated with visible inhomogeneities
- Hot spots not easily visible in microscopy



## **Bright spot origin: ITO agglomerations**

- Improved panel deconstruction
  - $\rightarrow$  delamination



SEM image of bright spot

Bright spots are consistently ITO-rich



EDS elemental mapping

10un

## **Hot Spot Fine Structure**

- Characteristic 'volcano' structure of hot spots
- Hot spots exhibit more Ohmic EL vs. voltage  $\rightarrow$  local shunts
- Hot spots often cluster



![](_page_5_Figure_5.jpeg)

#### Hot spot link to shorts

• Dark spots emerge from original hot spots

![](_page_6_Figure_2.jpeg)

## **Connecting to catastrophic failure**

- Early connection to catastrophic short failure (fractal-like growth of shorts)
- Volcano analog of short growth

![](_page_7_Picture_3.jpeg)

### **Emerging model of short growth**

![](_page_8_Picture_1.jpeg)

## The need for OLED thermal stability

- Automotive applications
  - Hot cars --> 85°C +
- Solid-state lighting
  - Panels operate at elevated temperature
  - Thermal stability closely connected to catastrophic failure
  - Intrinsic OLED lifetime ~  $exp(-E_A/kT)$

![](_page_9_Picture_7.jpeg)

![](_page_9_Picture_8.jpeg)

![](_page_9_Picture_9.jpeg)

OSRAM

## **Current status for small molecule OLEDs**

- Elevated temperature causes:
  - Crystallization/morphological changes
  - Expansion
  - Melting and/or vaporization
- Existing strategies to improve thermal stability:

![](_page_10_Figure_6.jpeg)

- TPD T<sub>g</sub>~60°C

- Additives:
  - Co-deposition of high T<sub>q</sub> small molecules
  - Co-deposition of inorganics (e.g. LiF)

![](_page_10_Picture_12.jpeg)

![](_page_10_Figure_13.jpeg)

D.E. Loy, et. al. Adv. Func. Mater. 12, 245 (2002)

## The additive route: Teflon AF

 Co-evaporate Teflon AF w/ small molecules

![](_page_11_Picture_2.jpeg)

![](_page_11_Figure_3.jpeg)

1. Evaporation

OLED

molecules

Teflon AF chain fragments

2. Deposition

substrate

3. Re-polymerization

![](_page_11_Picture_8.jpeg)

substrate

substrate

### **Evidence for polymer network**

• Ellipsometry of Teflon/NPD films  $\rightarrow$  Dissolve out NPD

![](_page_12_Figure_2.jpeg)

NPD+Teflon

NPD

Nanoporous Teflon network must exist

### Dilute organic semiconductors

- Dilution in insulating matrix can improve trap-limited transport
  - Ν •  $J \sim \left| \frac{1}{N_{f}} \right|$

а

Activation energy (eV)

0.45

0.40

0.35

0

Example: hole-only MEH-PPV / PVK 0

![](_page_13_Figure_4.jpeg)

20

![](_page_13_Figure_5.jpeg)

 $10^{3}$ 

0% MFH-PPV 125 nm

50% MFH-PPV 137 nm 25% MEH-PPV 121 nm

### NPD + Teflon AF

- Hole-only devices: ITO/NPD (60 nm)/AI
  - T<sub>g</sub> ~ 95°C
- Measured on and post-hot plate

![](_page_14_Picture_4.jpeg)

![](_page_14_Figure_5.jpeg)

#### NPD + Teflon AF

- Hole-only devices: ITO/NPD (60 nm)/AI
  - T<sub>g</sub> ~ 95°C
- Measured on and post-hot plate

![](_page_15_Picture_4.jpeg)

![](_page_15_Figure_5.jpeg)

### NPD + Teflon AF

- Hole-only devices: ITO/NPD (60 nm)/AI
  - T<sub>g</sub> ~ 95°C
- Measured on and post-hot plate

![](_page_16_Picture_4.jpeg)

![](_page_16_Figure_5.jpeg)

#### Summary

Hole-only device (50 nm)	Voltage at 10 mA/cm <sup>2</sup> (25°C)	"Shorted" Temp
Neat NPD	3.4 V	110°C
25% NPD/Teflon	2.2 V	250°C
50% NPD/Teflon	2.7 V	>260°C
80% NPD/Teflon	4.0 V	>260°C

## Conclusions

#### **OLED** panel failure

- Bright spots & Hot spots
- Temp. selective EL imaging
- Hot spots >> short precursors
- Nano >> Micro >> Macroshort

#### Thermal stability via Teflon

- Co-evap w/ HTLs
- Repolym to nanoscale Teflon network
- Improves injection & bulk transport
- >100°C thermal stability increase

![](_page_17_Figure_11.jpeg)

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![](_page_18_Picture_8.jpeg)

![](_page_18_Picture_9.jpeg)

![](_page_18_Picture_10.jpeg)

Energy Efficiency & Renewable Energy

![](_page_18_Picture_12.jpeg)

![](_page_18_Picture_13.jpeg)

![](_page_18_Picture_14.jpeg)